

Preliminary

MOS Memories

FUJITSU

■ MB83512-15

CMOS 524,288-Bit
Mask-Programmable
Read Only Memory

Description

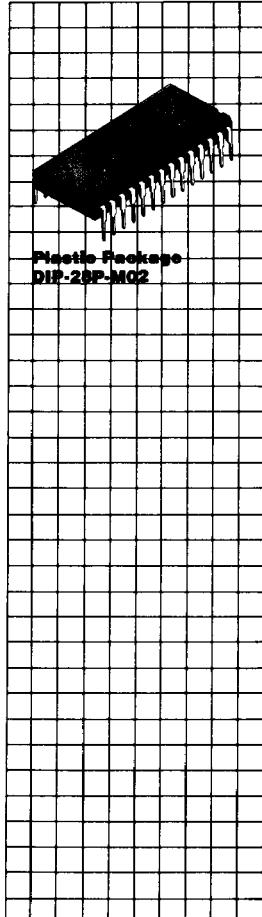
The Fujitsu MB83512 is a CMOS Si-gate mask-programmable static read only memory organized as 65,536 words by 8-bits.

The MB83512 has TTL-compatible I/O and TRI-state output level with fully-static operation (i.e. no need of clock signal) and single +5V power supply. The device is designed for applications such as character generator or program storage which require large memory capacity and high-speed/low-power operation.

The MB83512 is packaged in a 28-pin dual-in-line package and its pin-out is compatible with standard 28-pin EPROM.

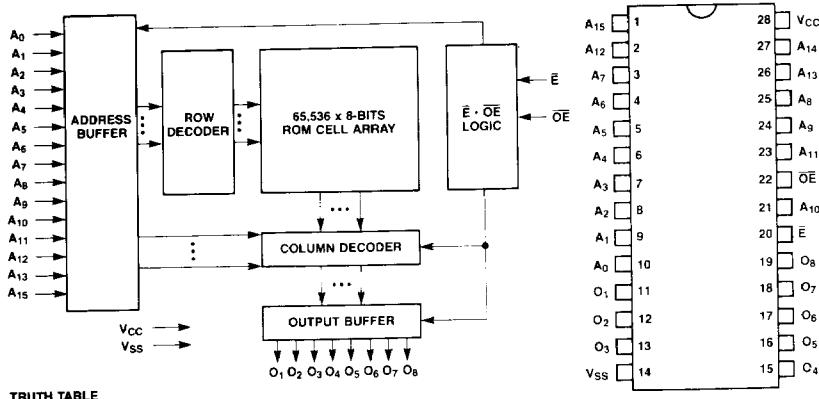
Features

- 65,536 words x 8-bits organization
- Fast access time:
150 ns max.
- Complete static operation:
No clock required
- ALL inputs and outputs are TTL compatible
- Three-state outputs
- +5V supply voltage
- Low power consumption:
220 mW (Operation)
16.5 mW (Standby, TTL input level)
- 275 μ W (Standby, CMOS input level)
- Standard 28-pin DIP



This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this impedance circuit.

**MB83512-15 Block Diagram
and Pin Assignment**



TRUTH TABLE

Ē	OĒ	MODE	OUTPUT	POWER CONSUMPTION MODE
H	X	NON-SELECTED	HIGH-Z	STANDBY
L	H	NON-SELECTED	HIGH-Z	ACTIVE
L	L	SELECTED	OUTPUT	ACTIVE

**Absolute Maximum Ratings
(See Note)**

Rating	Symbol	Value	Unit
Storage temperature range	T _{STG}	-45 to +125	°C
Temperature under bias	T _{BIAIS}	-10 to +85	°C
Supply voltage	V _{CC}	-0.3 to +7.0	V
Input voltage	V _{IN}	-0.5 to V _{CC} + 0.5	V
Output voltage	V _{OUT}	-0.5 to V _{CC} + 0.5	V

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Capacitance
(T_A = 25°C, f = 1 MHz)**

Parameter	Symbol	Min	Typ	Max	Unit
Output Capacitance (V _{OUT} = 0V)	C _{OUT}	10	pF		
Input Capacitance (V _{IN} = 0V)	C _{IN}	7	pF		

**Recommended Operating
Conditions
(Reference to GND)**

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	V _{CC}	4.5	5.0	5.5	V
Input low voltage	V _{IL}	-0.3		0.8	V
Input high voltage	V _{IH}	2.2		V _{CC} + 0.3	V
Ambient temperature	T _A	0		70	°C

DC Characteristics
(Recommended operating conditions unless otherwise noted.)

Parameter	Test Conditions	Symbol	MB83512-15		
			Min	Max	Unit
Standby supply current	$\bar{E} = V_{IH}$	I_{SB1}	3	mA	
	$\bar{E} = V_{CC}, V_{IN} = GND \text{ or } V_{CC}$	I_{SB2}	50	μA	
Active supply current	$\bar{E} = V_{IL}$, minimum cycle	I_{CC}	40	mA	
Input leakage current	$V_{IN} = 0V \text{ to } V_{CC}$	I_{LI}	-10	10	μA
Output leakage current	$\bar{E} = V_{IH}$, or $\bar{OE} = V_{IH}$	I_{LO}	-10	10	μA
Output high voltage	$I_{OH} = -400 \mu A$	V_{OH}	2.4	V	
Output low voltage	$I_{OL} = 2.1 \text{ mA}$	V_{OL}	0.4	V	

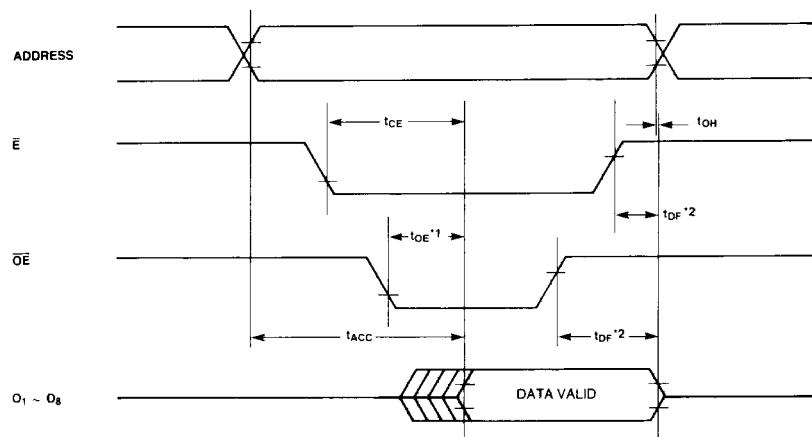
AC Characteristics
(Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	MB83512-15		
		Min	Typ	Max
Address access time ($\bar{E} = \bar{OE} = V_{IL}$)	t_{ACC}	150	ns	
Chip enable access time ($\bar{OE} = V_{IL}$)	t_E	150	ns	
Output enable access time ¹	t_{OE}	80	ns	
Output disable time ²	t_{DF}	60	ns	
Output hold time	t_{OH}	0		ns

Notes: ¹ \bar{OE} may be delayed up to $(t_{ACC} - t_{OE})$ after the falling edge of \bar{E} without impact on t_{ACC} .

² t_{DF} is specified from \bar{OE} or \bar{E} , whichever occurs earlier.

Timing Diagram



NOTES: ¹ \bar{OE} MAY BE DELAYED UP TO $(t_{ACC} - t_{OE})$ AFTER THE FALLING EDGE OF \bar{E} WITHOUT IMPACT ON t_{ACC} .

² t_{DF} IS SPECIFIED FROM \bar{OE} OR \bar{E} , WHICHEVER OCCURS EARLIER.

